


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

| | | |
|-----------------------------|---|--------------------------------------|
| 1.1 Company |  | STMicroelectronics International N.V |
| 1.2 PCN No. | AMS/21/12593 | |
| 1.3 Title of PCN | Reflow profile recommendation for selected BlueNRG modules | |
| 1.4 Product Category | See product list | |
| 1.5 Issue date | 2021-03-09 | |

2. PCN Team

| | |
|----------------------------------|-------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | NEMETH KRISZTINA |
| 2.1.2 Phone | +49 89460062210 |
| 2.1.3 Email | krisztina.nemeth@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Marco VENERI |
| 2.1.2 Marketing Manager | Marco VENERI |
| 2.1.3 Quality Manager | Jean-Marc BUGNARD |

3. Change

| | | |
|--------------------------|--|-----------------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| General Product & Design | Modification of datasheet : Errata/error fix | Back end plant : ASE Korea |

4. Description of change

| | | |
|--|--|--|
| | Old | New |
| 4.1 Description | Peak temperature (Tp) = 245 (-0) °C Time within 5°C of peak temperature (Tp-5°C) = min 30 s | Peak temperature (Tp) = 240 + 0 °C Time within 5°C of peak temperature (Tp-5°C) = 10-20 sec |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No impact | |

5. Reason / motivation for change

| | |
|-----------------------------|--|
| 5.1 Motivation | To avoid any prohibited liquidus state of module solder joints during customer reflow. |
| 5.2 Customer Benefit | QUALITY IMPROVEMENT |

6. Marking of parts / traceability of change

| | |
|------------------------|-----|
| 6.1 Description | N/A |
|------------------------|-----|

7. Timing / schedule

| | |
|--|--------------|
| 7.1 Date of qualification results | 2021-02-01 |
| 7.2 Intended start of delivery | 2021-05-15 |
| 7.3 Qualification sample available? | Upon Request |

8. Qualification / Validation

| | | | |
|---|---|-------------------|------------|
| 8.1 Description | 12593 BLUENRG-Modules_Reflow_Profile_Change.pdf | | |
| 8.2 Qualification report and qualification results | Available (see attachment) | Issue Date | 2021-03-09 |

9. Attachments (additional documentations)

| |
|---|
| 12593 Public product.pdf 12593 BLUENRG-Modules_Reflow_Profile_Change.pdf |
|---|

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | BLUENRG-M0A | |
| | BLUENRG-M2SP | |

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